

ABSTRACT

A process for producing an electrodeposited copper foil with its surface prepared, comprising the steps of: subjecting an electrodeposited copper foil having a shiny side and a matte side whose average surface roughness (Rz) is in the range of 2.5 to 10 μm to the first mechanical polishing so that the average surface roughness (Rz) of the matte side becomes 1.5 to 6 μm ; and subjecting the matte side having undergone the first mechanical polishing to at least one further mechanical polishing so that the average surface roughness (Rz) of the matte side becomes 1.0 to 3.0 μm . The protrudent parts of the matte side are selectively polished by the first mechanical polishing, and the surface having undergone the first mechanical polishing is further subjected to the second and any ensuing mechanical polishings under milder conditions. Thus, a highly planar polished face with excellent surface properties can be obtained. Moreover, depressed parts are not polished, so that the amount of copper lost by the polishings is extremely minute. The use of the electrodeposited copper foil with its surface prepared according to the present invention enables forming a wiring pattern of extremely fine pitch.

